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## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
88	AA	5 6 5 2 0 4 2	7/29/97	KAWAKITA ETAL	428	209	
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## FOREIGN PATENT DOCUMENTS

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## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

88	AR	R LASKY, "NEW PCB TECHNOLOGIES EMERGE FOR HIGH-DENSITY INTERCONNECT" ELECTRONIC PACKAGING AND PRODUCTION, APRIL 1998, PAGES 75-78
88	AS	HANG ETAL, "DEVELOPMENT OF HIGH CONDUCTIVITY LEAD (Pb)-FREE CONDUCTING ADHESIVES" IEEE TRANSACTIONS ON COMPONENTS, MANUFACTURING TECHNOLOGY, PART A, VOL 21, NO 1, MARCH 1998, PAGES 18-22
88	AT	HANG ETAL, "DEVELOPMENT OF LOW COST, LOW TEMPERATURE CONDUCTIVE ADHESIVES", PROCEEDINGS OF THE 48TH ELECTRONIC COMPONENTS & TECHNOLOGY CONFERENCE, SEATTLE, WASH., MAY 1998, PAGES 1031-1035

EXAMINER

Jonathan Johnson

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98	AL	GONZALEZ ET AL, "EPOXY-BASED AQUEOUS-PROCESSABLE PHOTOELECTRIC DRY FILM AND CONDUCTIVE VIA PLOT FOR PCB BUILDUP AND IC PACKAGING," PAGE 48TH ELECTRONIC COMPONENTS TECH. CONF. SEATTLE WASH. NOV 1998, P139-143
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